ABSTRACT OF THE DISCLOSURE

ELECTRONIC PART

The present invention provides an electronic part having a high heat resistance and a superior junction characteristic in a junction via soldering or wire bonding in a package comprising any of a lead frame, an organic substrate, or a ceramic substrate. The electronic part of the present invention comprises: a chip having joining terminals; and a substratum having a chip-mounting section on which the chip is loaded via the joining terminals and packaging terminals by which the chip is mounted on a substrate, wherein at least any of a group consisting of said joining terminals of the chip, chip-mounting section of the substrate, and packaging terminals is/are formed with a germanium-containing palladium plating film.

Enc : Figure 1